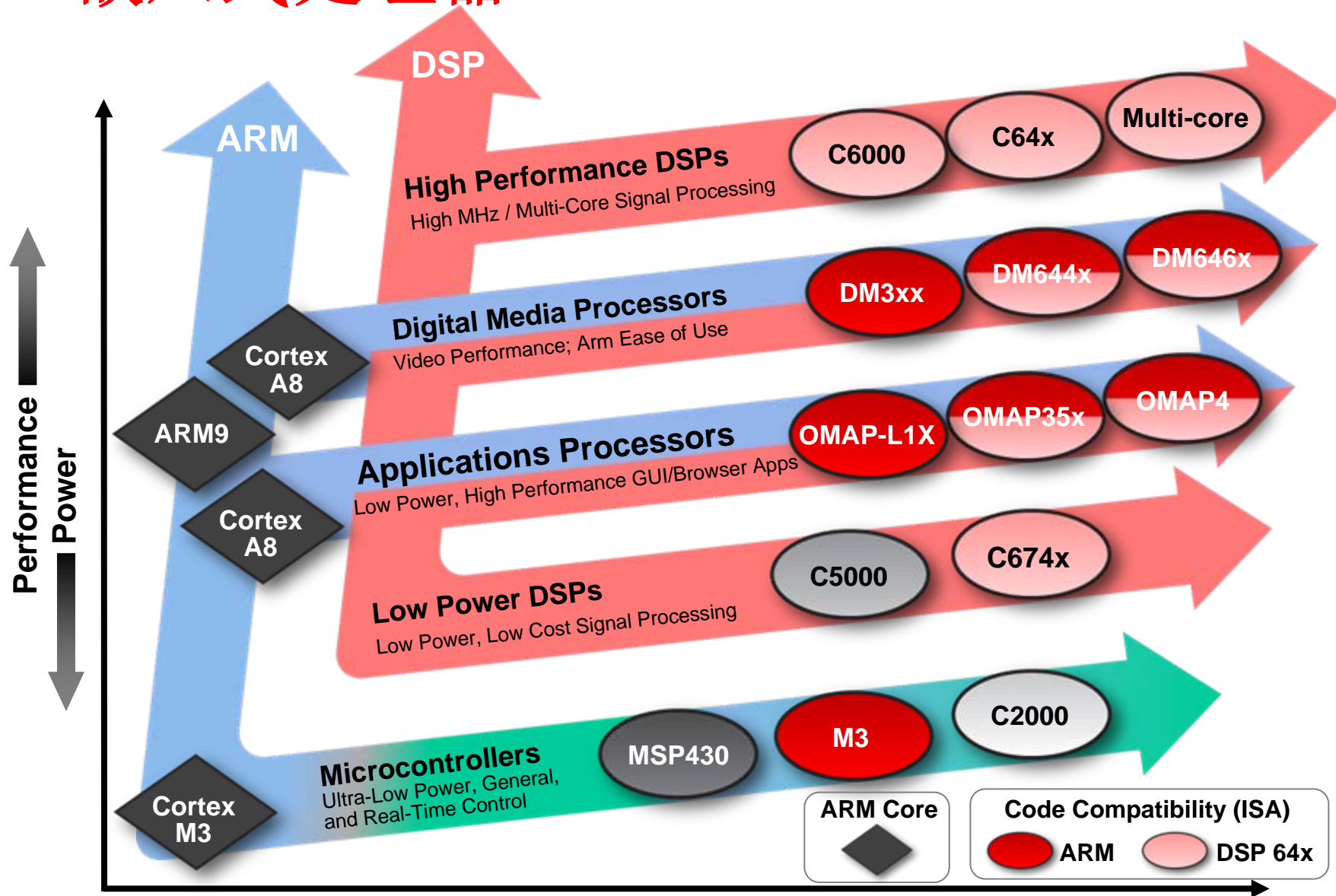


OMAP-L1x 基于ARM处理器

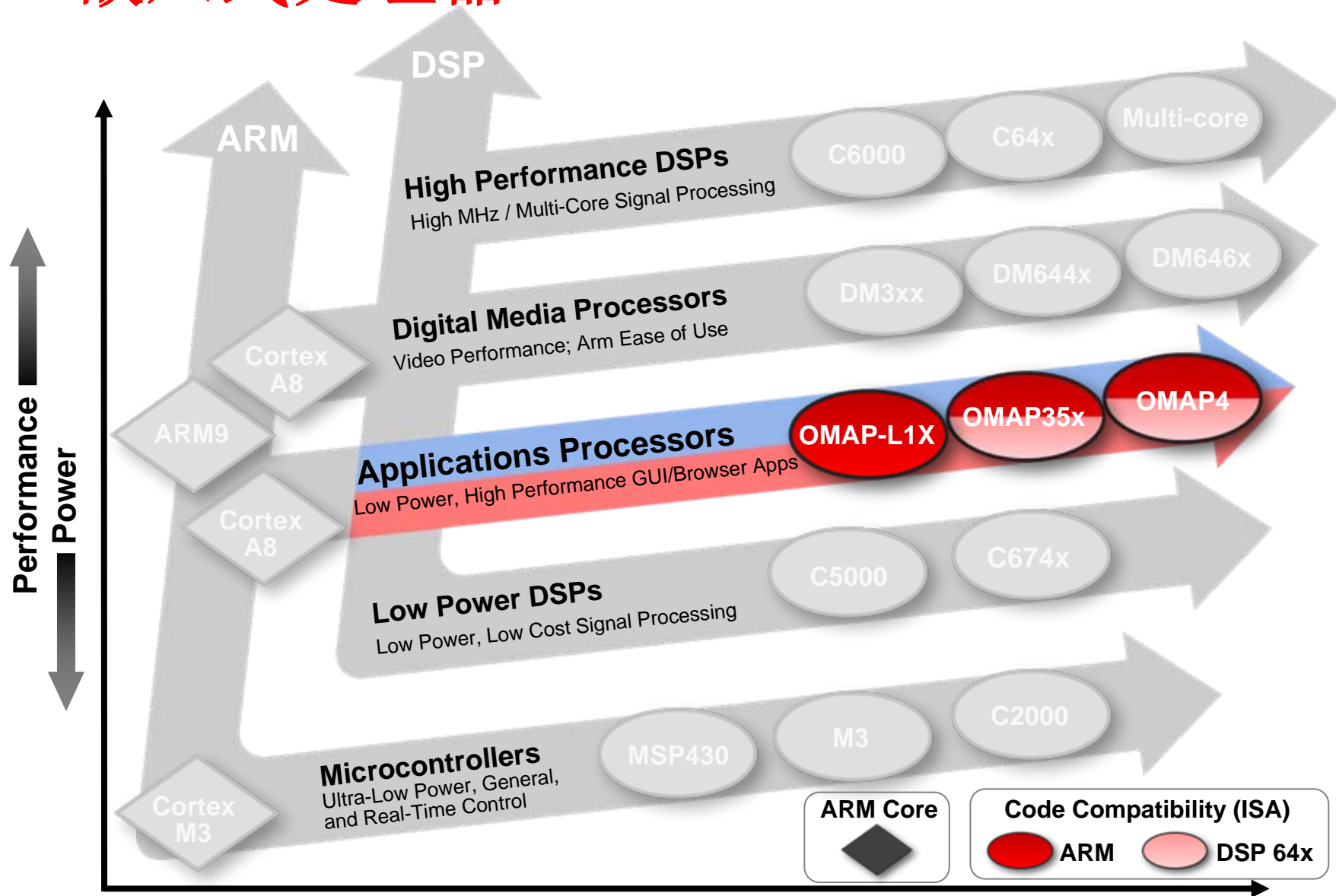


One Day, Multiple Solutions

TI 嵌入式处理器



TI 嵌入式处理器



OMAP-L1x: 无可比拟的互联选项与低功耗的ARM9 和可选择的C674x DSP内核

灵活的系统接口
&网络互联

- SATA, uPP, EMAC, USB PHY
- System cost savings in the range of 15%

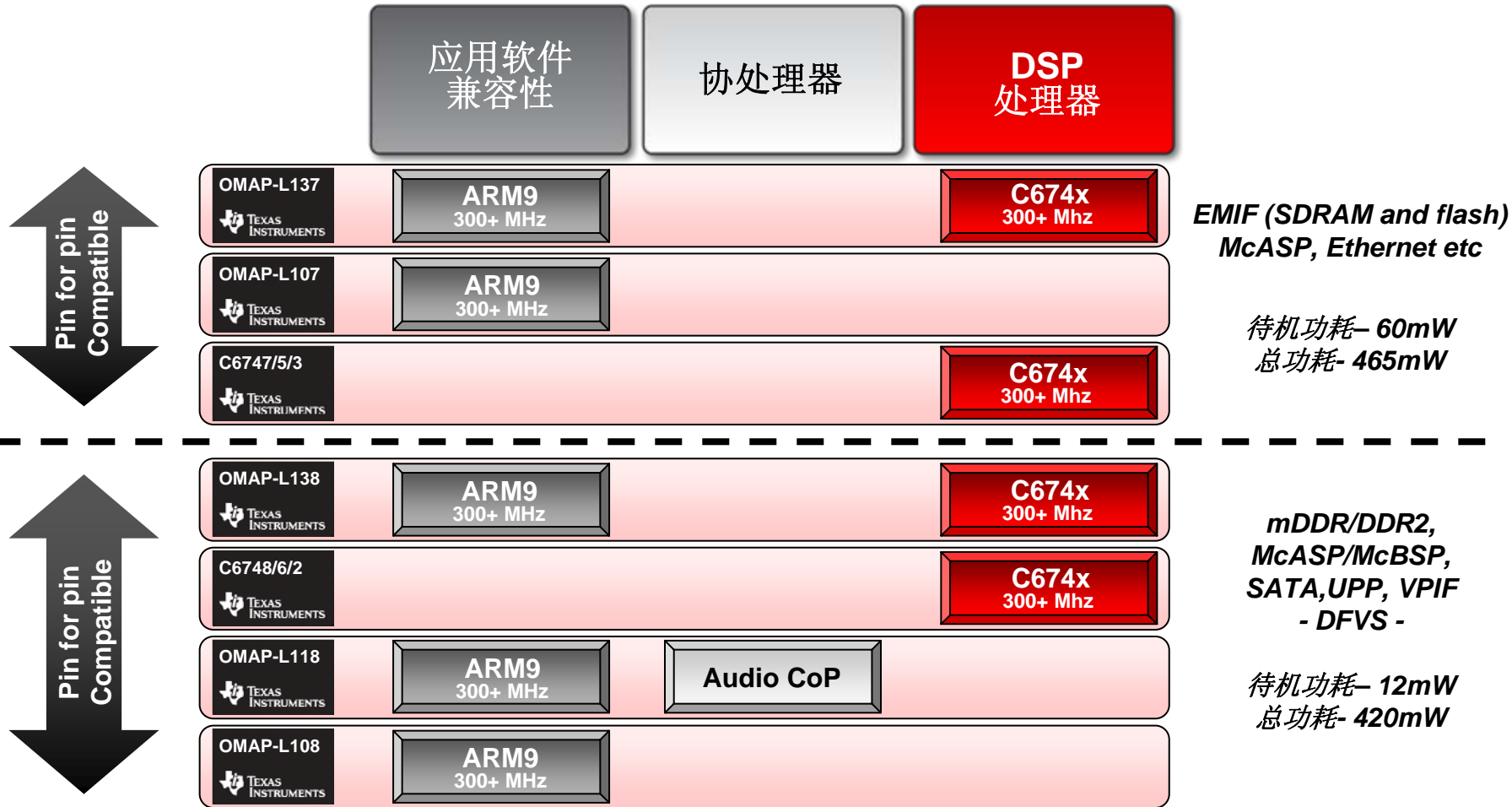
在性能和功耗上
最优化你的系统

- Industry's lowest power floating-point DSP
- Power management software
- Dynamic voltage frequency scaling

开发变得
更加容易

- Fixed- & floating-point with C674x core
- C67x+ & C64x+ code reuse
- Pin-to-pin compatibility

OMAP-L1x Roadmap—低于\$15 (10Ku)



C674x –DSP only
OMAP-L13x – ARM + Floating-Point DSP
OMAP-L118 – ARM + Co-Processor
OMAP-L10x – ARM only

TI's OMAP-L1x 应用处理器为以下这些应用而量身订制:

应用如下:

Bar code
scanners



Test and
measurement

SDR



Portable
medical



Industrial
monitoring



Medical
monitoring



Sonar

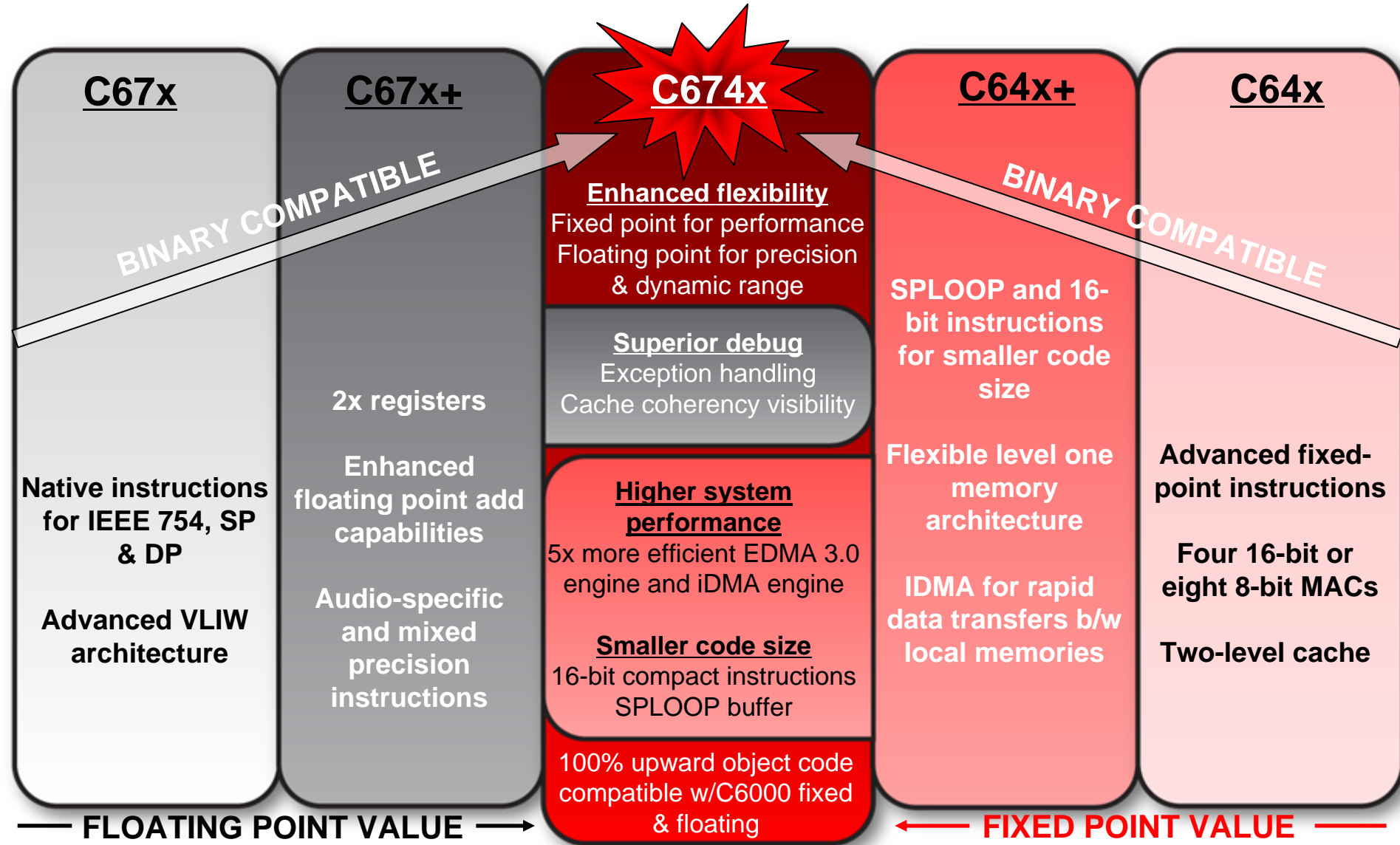


设计需求

- 高度集成SoC
- 特有的外设互联
- 低功耗为便携设备
apps: 12mW – 465mW*
- 支持各种不同等级的操作系统

* For typical use case scenarios

C674x DSP 内核: 同时支持浮点定点运算

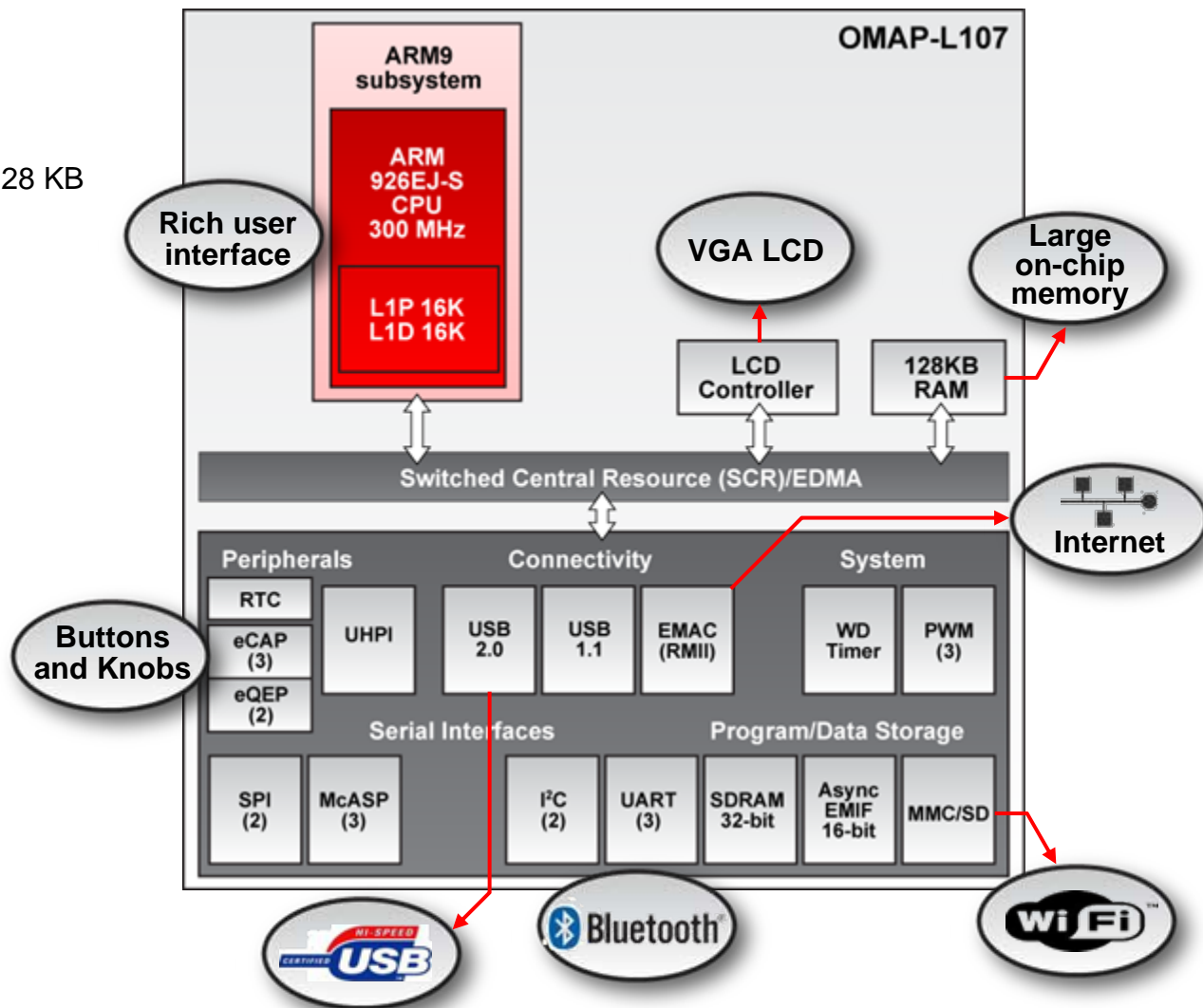


OMAP-L107 处理器(ARM9)—预计

时间表: TMX – Oct 09; TMS – 1Q10

CPU 内核

- ARM926E-JS™ up to 300 MHz
- 存储
 - ARM: 16K L1D, 16K L1P, 64K ROM, 128 KB L3 RAM
- 功耗(1.2V core, 1.8/3.3V IOs)
 - 活跃 < 490 mW @ 300MHz/1.2V/70C
 - 待机 < 60 mW @ 300MHz/1.2V/25C
- 封装
 - 17 x17mm BGA (1.0mm pitch)
 - 和 OMAP-L137, C6743/5/7管脚兼容
- 工作温度范围
 - 商用温度器件
 - 节点温度, TJ: 0 – 90 C
 - 周围温度, TA: 0 – 70 C
 - 汽车温度器件
 - 节点温度, TJ: -40 – 125 C
 - 周围温度, TA: -40 – 105 C
- 价格: \$7.85 @ 1Ku

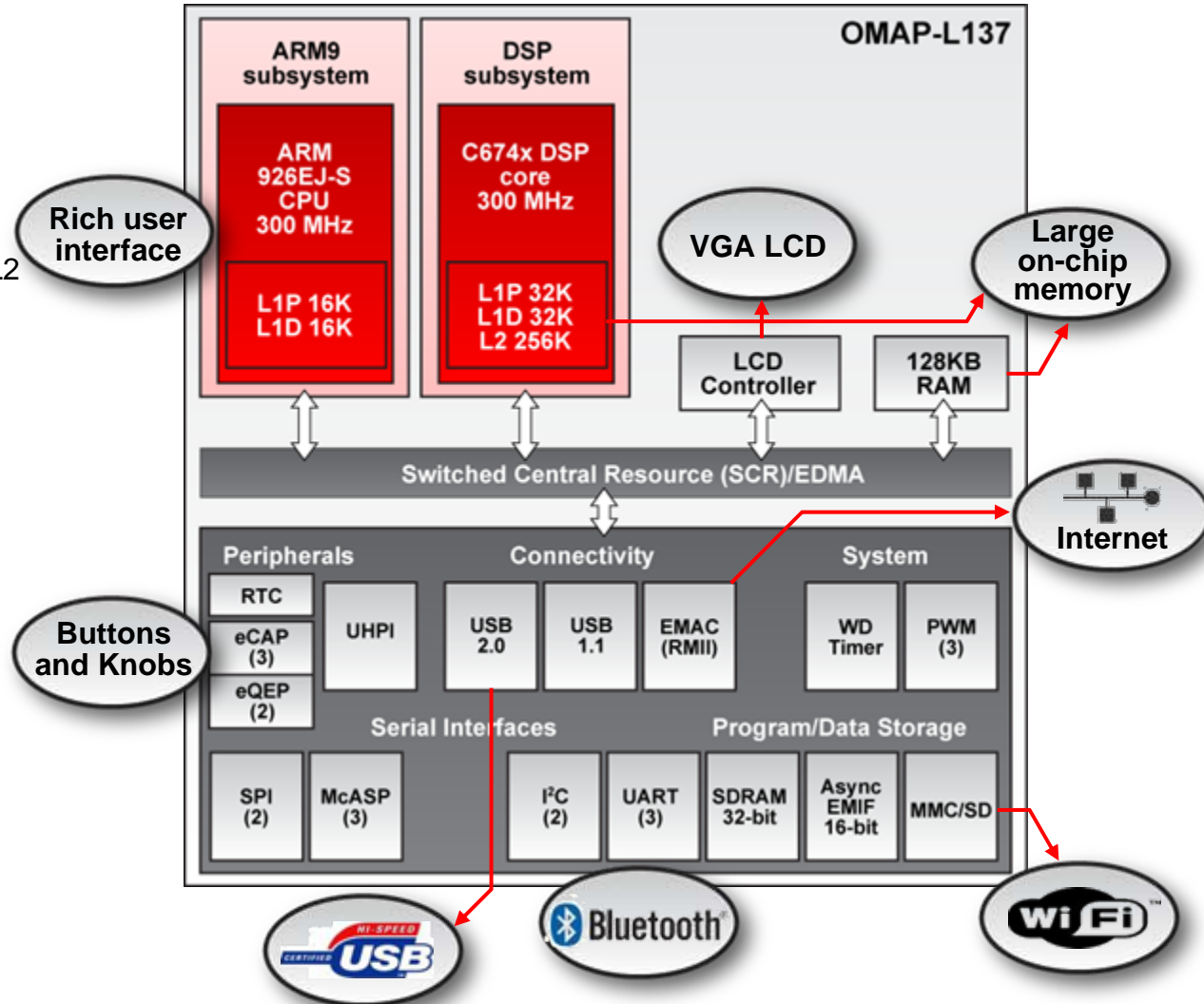


OMAP-L137 处理器(C674x DSP + ARM9)

时间表: TMX – Now; TMS – 1Q10

CPU 内核

- ARM926E-JS™ up to 300 MHz
- C674x DSP core up to 300 MHz
- 存储
 - ARM: 16K L1D, 16K L1P, 64K ROM
 - DSP: 32 KB L1D, 32 KB L1P, 256 KB L2
 - Shared: 128 KB RAM
- 功耗(1.2V core, 1.8/3.3V IOs)
 - 活跃 < 465 mW @ 300MHz/1.2V/70C
 - 待机 < 60 mW @ 300MHz/1.2V/25C
- 封装
 - 17 x17mm BGA (1.0mm pitch)
 - 和C6743/7管脚完全兼容
- 工作温度范围
 - 商用器件温度
 - 节点温度, TJ: 0 – 90 C
 - 周围温度, TA: 0 – 70 C
 - 汽车级器件温度
 - 节点温度, TJ: -40 – 125 C
 - 周围温度, TA: -40 – 105 C
- 价格: \$16.35 @ 1Ku



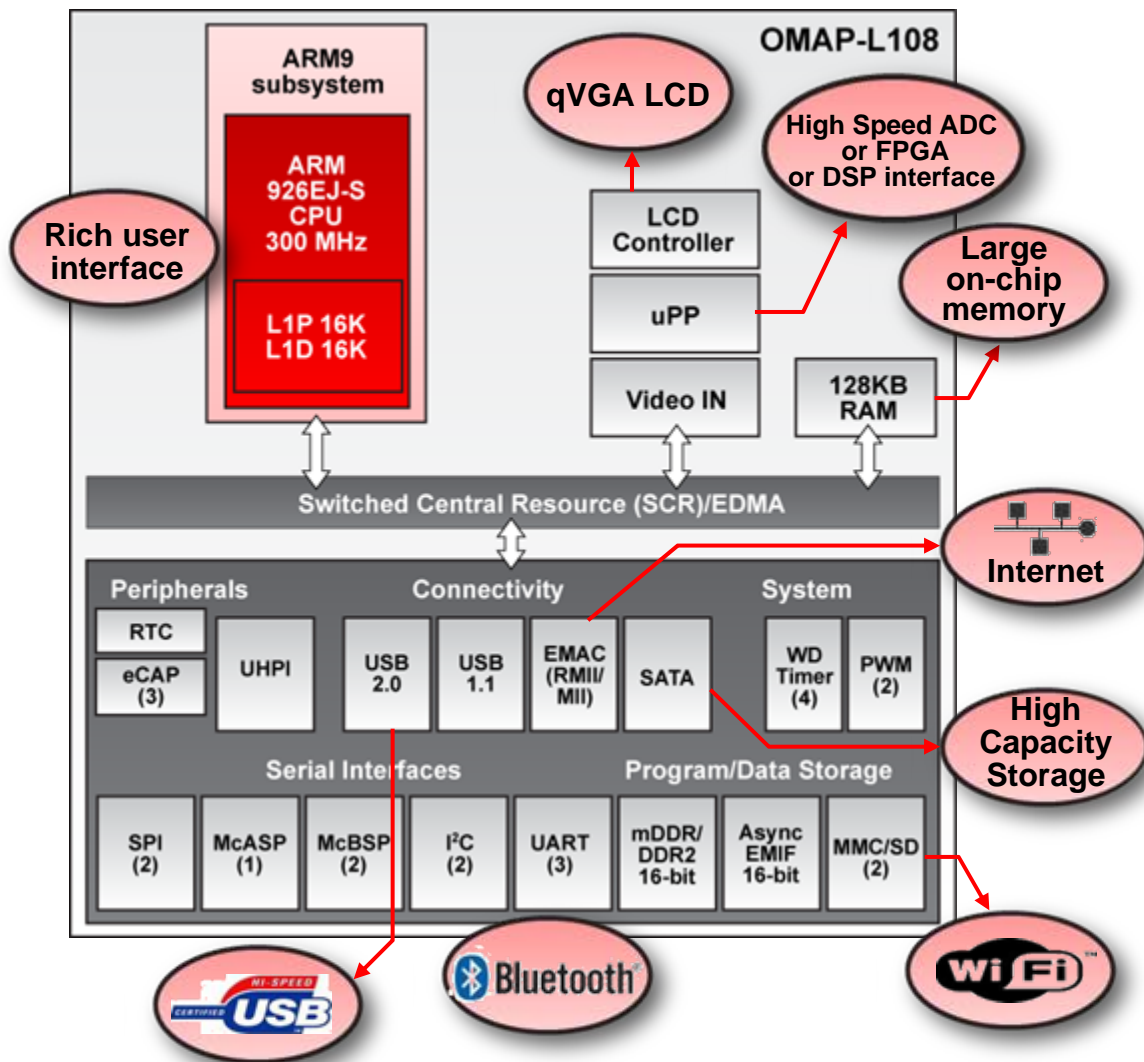
OMAP-L108 处理器(ARM9)—预计

时间表: TMX – Oct 09; TMS – 1Q10

功耗

(1.0-1.2V Core, 1.8/3.3V IOs)

- 总功耗 < 440 mW @ 300MHz, 1.2V, 25C
- 待机功耗
 - < 15mW @ 1.0V/ 25C;
 - < 20mW @ 1.2V/25C
- 封装选择
 - 13 x13mm nFBGA (65nm)
 - 16x16mm BGA (0.8mm)
 - 和OMAP-L138,L118, C6748/6/2管脚完全兼容
- 应用
 - SDR, Portable Catalog, Bar Code Scanners, Portable Communications, Portable Medical, Portable Audio
- 工作温度范围
 - 商用器件温度
 - 节点温度, TJ: 0 – 90 C
 - 周围温度, TA: 0 – 70 C
 - 汽车级器件温度
 - 节点温度, TJ: -40 – 125 C
 - 周围温度, TA: -40 – 105 C
- 价格: \$9.00 @ 1Ku



新的OMAP-L138 (ARM9 + C674x DSP)

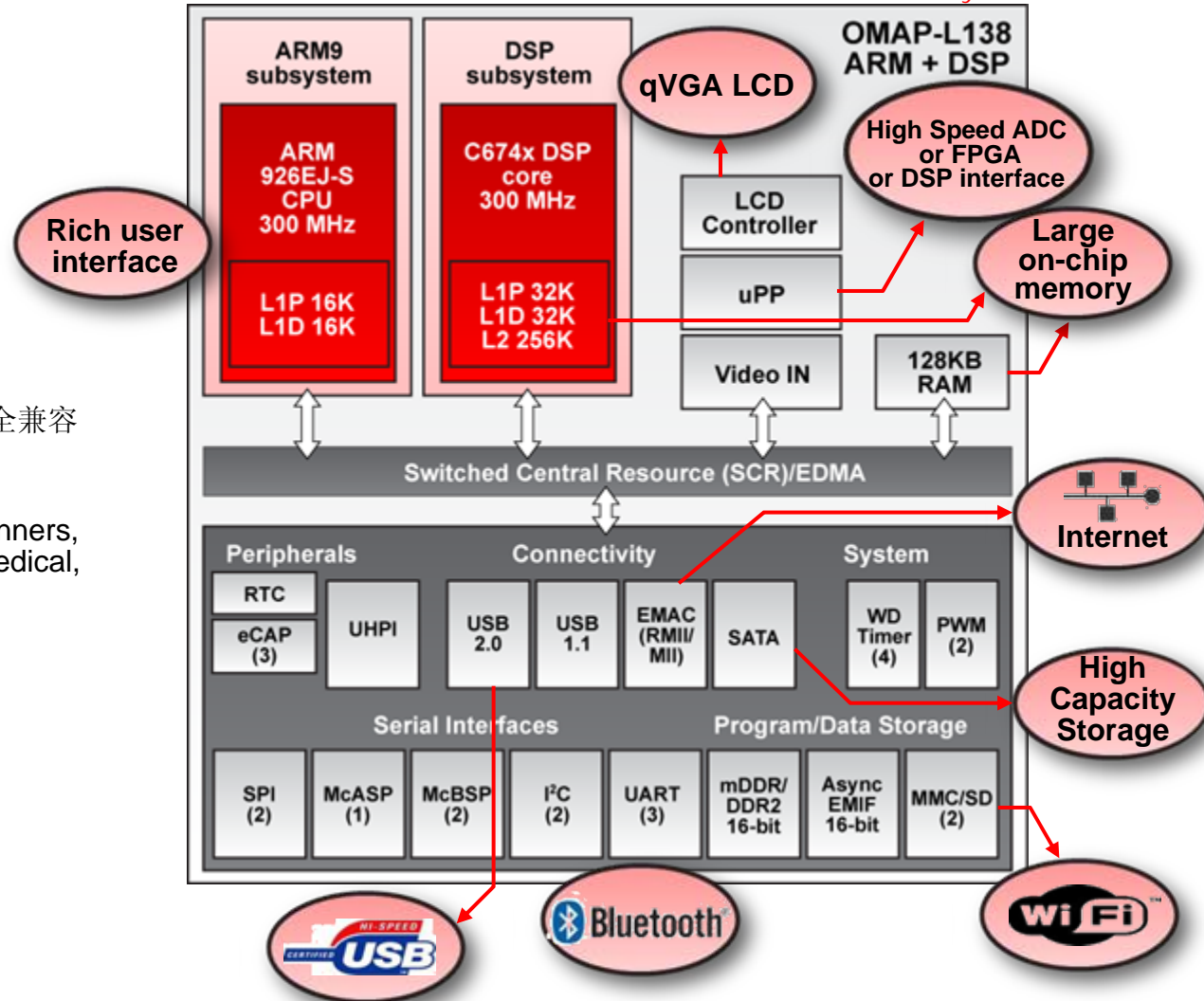
时间表: TMX – Now; TMS – 1Q10

EVM Available July '09

功耗

(1.0-1.2V Core, 1.8/3.3V IOs)

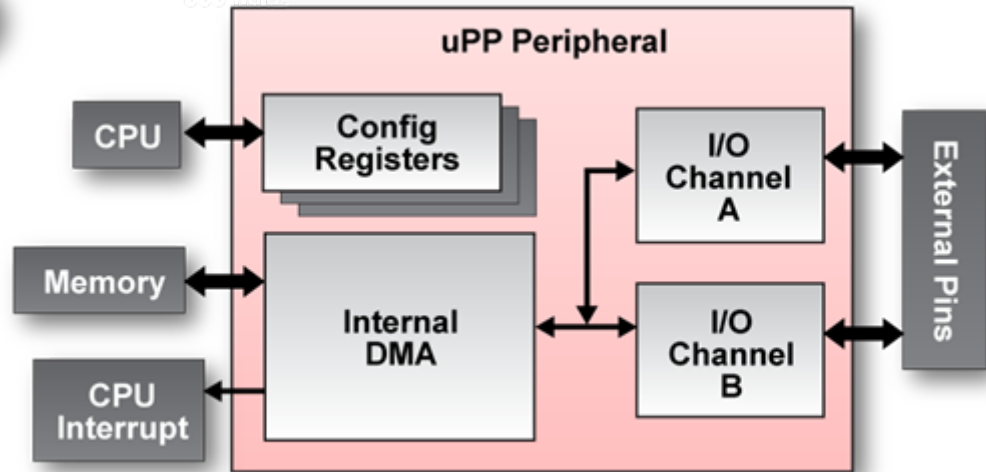
- 总功耗 < 440 mW @ 300MHz, 1.2V, 25C
- 待机功耗
 - < 12mW @ 1.0V/ 25C;
 - < 20mW @ 1.2V/25C
- 封装选择
 - 13 x13mm nFBGA (65nm)
 - 16x16mm BGA (0.8mm)
 - 和OMAP-L118/108, C6748/6/2管脚完全兼容
- 应用
 - SDR, Portable Catalog, Bar Code Scanners, Portable Communications, Portable Medical, Portable Audio
- 工作温度范围
 - 商用器件温度
 - 节点温度, TJ: 0 – 90 C
 - 周围温度, TA: 0 – 70 C
 - 汽车级器件温度
 - 节点温度, TJ: -40 – 125 C
 - 周围温度, TA: -40 – 105 C
- 价格: \$18.60 @ 1Ku



通用并行端口 (uPP) 扩展系统互联选项

什么是 uPP?

- 高速并行数据端口
- 两个双向的和独立的16位通道
- 内部DMA使得数据I/O效率更高
- 简单的I/O协议



uPP有什么用?

- 高效的DSP+FPGA 系统被高速数据I/O使能
- 使能多DSP系统可以设计成各种不同的拓扑结构
- 与高速ADCs 和DACs高速互联

配置	流量(MB/s)
1 Ch, 16-bit	120
2 Ch, 1 Way, 8-bit	120
2 Ch, 1 Way, 16-bit	160
2 Ch, 2 Way, 16-bit	240
HPI (16-bit)	50

OMAP-L137/TMS320C6747 浮点开发套件

用来在以下器件的开发: OMAP-L137, OMAP-L107, C6747, C6745 & C6743



Available Now: ~~\$399~~ \$349

Part Number: TMDXOSKL137BET

Hardware

- OMAP-L137 – ARM9 + C674x DSP
- 24-bit stereo CODEC
- Four 3.5 millimeter audio jacks
- 64Mb SPI Flash memory
- 512Mb SDRAM
- ETH MAC, USB 2.0, USB 1.1, MMC/SD, LCDc
- HPI, McASP & I2C interface header emulation
- On-board standard JTAG interface
- Embedded JTAG support via USB
- +5V universal power supply
- Expansion ports for plug-in modules

Software

- Code Composer Studio™ IDE
- Simulator included
- DSP/BIOS™ RTOS, eXpressDSP, and Monta Vista Linux Pro 5.0 Software support
- Fast run-time library available on the web
- MATLAB/Simulink Support (FUTURE)
- LabVIEW for Embedded Applications Support (FUTURE)
- Quick Start Guide and technical reference

OMAP-L138: 满足不同客户需求的工具

用来在以下器件的开发: **OMAP-L138, OMAP-L118, OMAP-L108, C6748, C6746 & C6742**

独立的系统单元

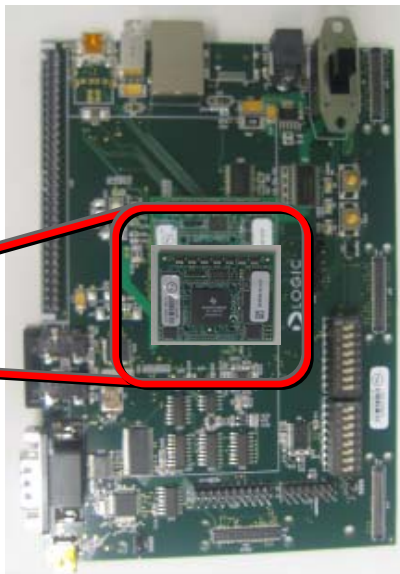
- OMAP-L138 processor
- 64 or 128MB mDDR
- Ethernet PHY

**Available from Logic for ~\$99*



**Small FF
Confirmed mDDR
design**

PN: SOMOAPL138-10-1602AHCR
for 128MB mDDR support
PN: SOMOAPL138-10-1502AHCR
For 64MB mDDR support



+



实验板

Only \$149

- OMAP-L138 SOM
- 64MB mDDR
- **Access to key peripherals:**
 - SATA, USB, EMAC, Audio
- TPS65070 power management
- DSP/BIOS™ peripheral drivers
- CCStudio™ 3.3
- **Community supported**
- **Available from TI & Logic for \$149, \$99*

TI PN: TMDXL138LOGIGEXP-B
Logic PN: SDK-OMAPL138-10-6408R

**Open source
Linux peripheral
drivers**

OMAP-L138/C6748 EVM

- **Full peripheral access:** SATA, uPP, EMAC, USB 2.0/1.1 and MMC/SD, VPIF, LCDC
- Software included
- TI supported
- LCD display option

**Available from TI for ~~\$849~~ \$799*

TI PN: TMDXOSKL138BET

**Additional
C6748 SOM**

**MCU Day
减价\$50**

OMAP-L1x: 无可比拟的互联选项和高性能的ARM9 和可选择的C674x DSP内核

灵活的系统接口
&网络互联

- SATA, uPP, EMAC, USB PHY
- System cost savings in the range of 15%

在性能和功耗上
最优化你的系统

- Industry's lowest power floating-point DSP
- Power management software
- Dynamic voltage frequency scaling

开发变得
更加容易

- Fixed- & floating-point with C674x core
- C67x+ & C64x+ code reuse
- Pin-to-pin compatibility

备注

TI's C674x 低功耗浮点DSPs 为以下应用而定制:

应用如下:

Fingerprint identification



Test and measurement

Robotics



Audio Effects

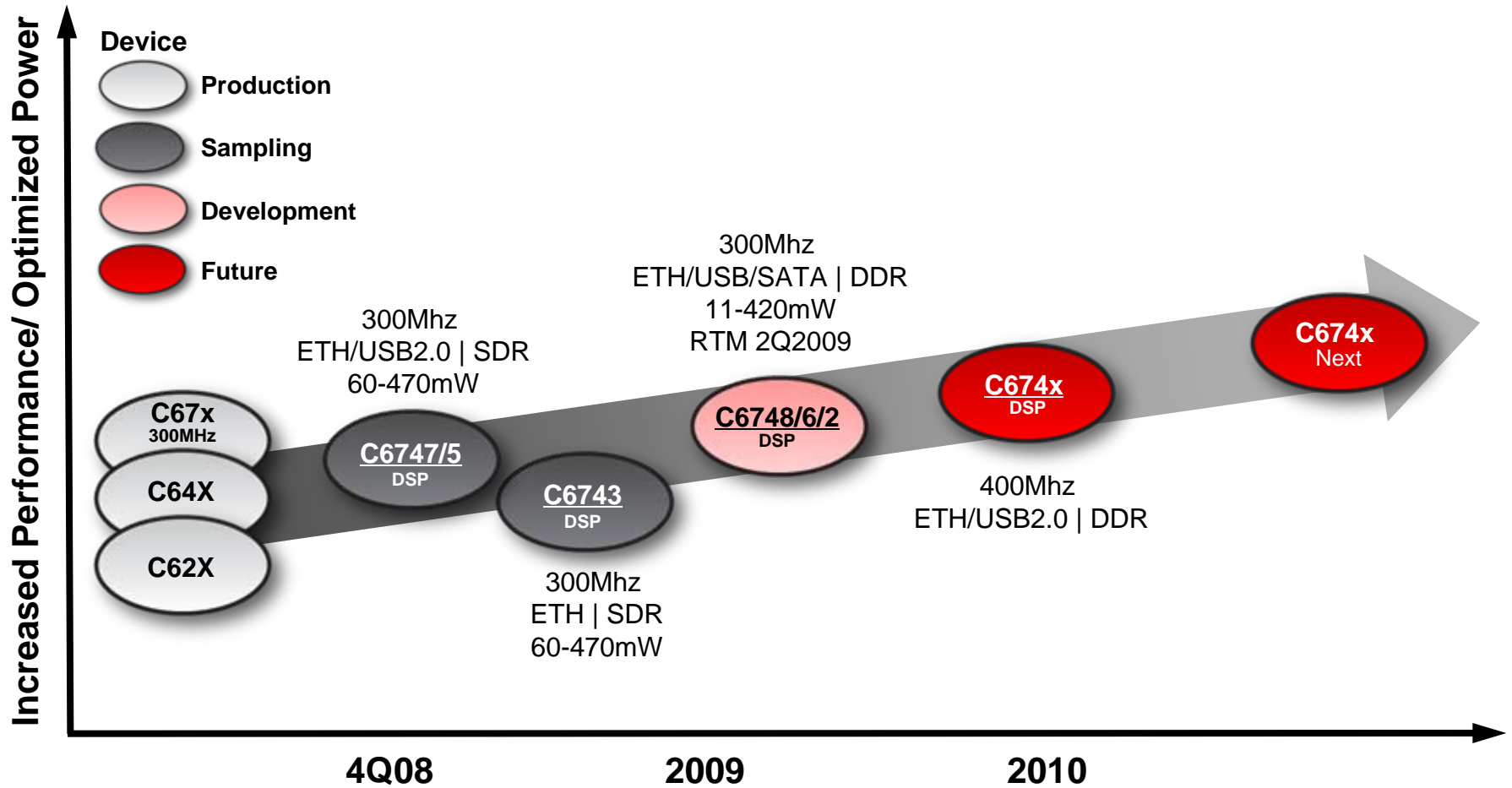


Audio applications

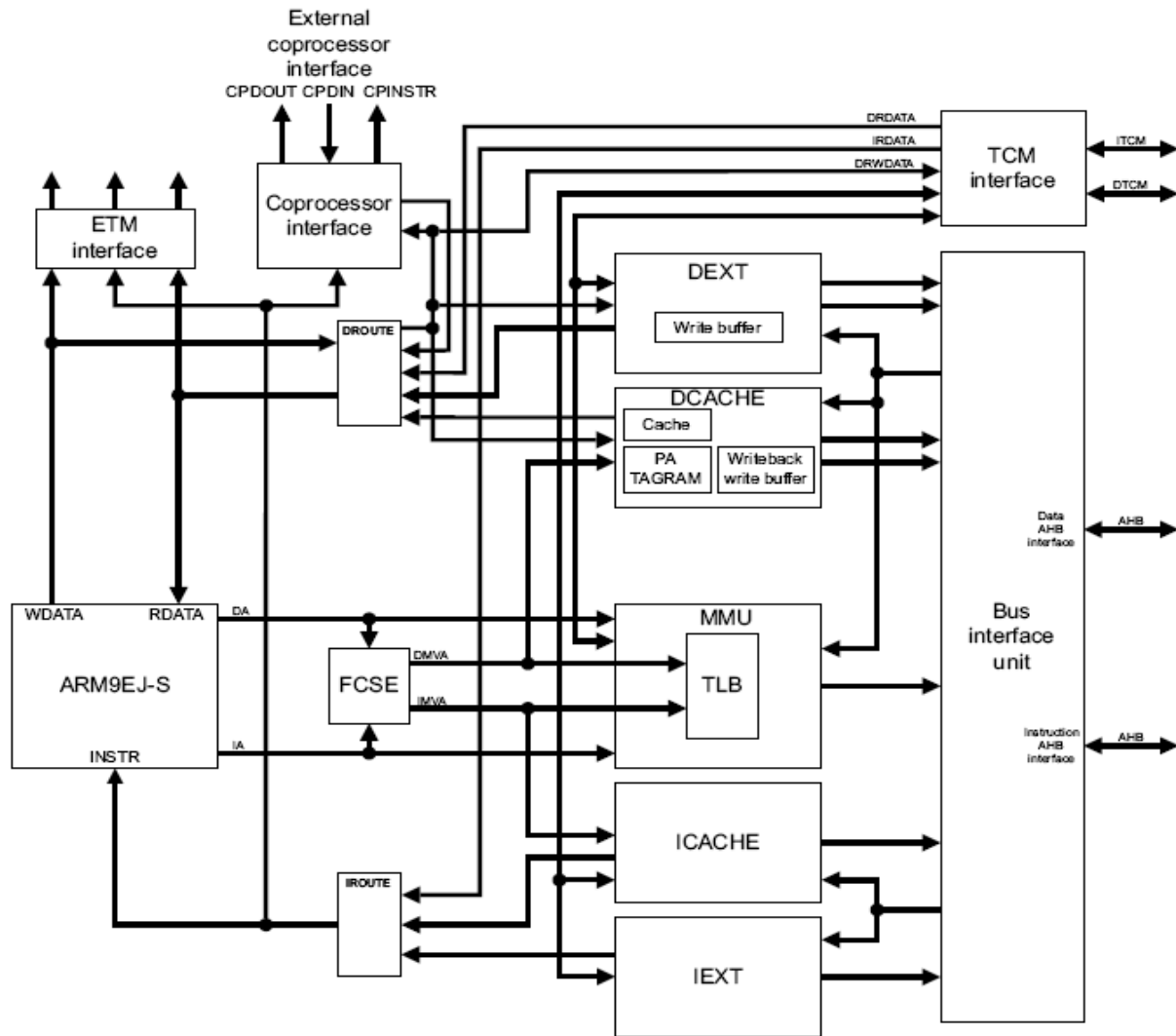
设计需求:

- Performance up to 2400MMACs
- Low active power
- Low standby power
- High precision
- Floating & fixed-point in a single core
- Code reuse

低功耗C674x浮点DSP roadmap



ARM926EJ-S 结构图



TMS320C674x DSP 内核

